

Sumikon® EME-7720R

Epoxy; Epoxide

Sumitomo Bakelite Co., Ltd.

Message:

Sumikon 7700-Series compounds are multi-functional-type molding compounds developed for overmolded BGA packages.

General Information			
Features	Low hygroscopicity		
Uses	Semiconductor molding compound		
Forms	Liquid		
Processing Method	Enclosure		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.99	g/cm ³	ASTM D792
Water Absorption (24 hr)	0.30	%	ASTM D570
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus (25°C)	23100	MPa	ASTM D790
Flexural Strength (25°C)	177	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	202	°C	ASTM E1356
Thermal Conductivity	0.79	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	1.0E+13	ohms·cm	ASTM D257
Thermoset	Nominal Value	Unit	
Demold Time (175°C)	0.50 - 1.7	min	
Post Cure Time (175°C)	2.0 - 8.0	hr	

Additional Information

Spiral Flow, SB-U-03-003: 80 cmGel Time, SB-U-03-005, 175°C: 30 secThermal Expansion, SB-U-02-002, TTg: 4.1 E-5/°CFlexural Strength, SB-U-01-001, 240°C: 44.1 MPaFlexural Modulus, SB-U-01-002, 240°C: 2650 MPaUL-94 Flame Class, SB-U-03-003: V-0Extracted Na+, SB-U-04-043: <1 ppmExtracted Cl-, SB-U-04-043: 5 ppmTransfer Pressure: 687-1177 MPa

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